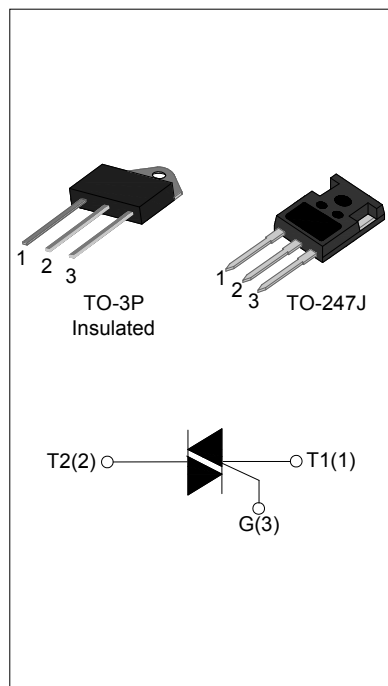




### DESCRIPTION:

With high ability to withstand the shock loading of large current, JST26 series provide high dv/dt rate with strong resistance to electromagnetic interface. With high commutation performances, 3 quadrants products especially recommended for use on inductive load. From all three terminals to external heatsink, JST26Z provide a rated insulation voltage of 2500 V<sub>RMS</sub>, complying with UL standards (File ref: E252906).



### MAIN FEATURES

Symbol	Value	Unit
I <sub>T(RMS)</sub>	25	A
V <sub>DRM</sub> / V <sub>RRM</sub>	600/800	V

### ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Storage junction temperature range	T <sub>stg</sub>	-40-150	°C
Operating junction temperature range	T <sub>j</sub>	-40-125	°C
Repetitive peak off-state voltage (T <sub>j</sub> =25°C)	V <sub>DRM</sub>	600/800	V
Repetitive peak reverse voltage (T <sub>j</sub> =25°C)	V <sub>RRM</sub>	600/800	V
Non repetitive surge peak Off-state voltage	V <sub>DSM</sub>	V <sub>DRM</sub> + 100	V
Non repetitive peak reverse voltage	V <sub>RSM</sub>	V <sub>RRM</sub> + 100	V
RMS on-state current	TO-3P(Ins) (T <sub>C</sub> =100°C)	25	A
	TO-247J (T <sub>C</sub> =110°C)		
Non repetitive surge peak on-state current (full cycle, F=50Hz)	I <sub>TSM</sub>	250	A
I <sup>2</sup> t value for fusing (tp=10ms)	I <sup>2</sup> t	340	A <sup>2</sup> s
Critical rate of rise of on-state current (I <sub>G</sub> = 2 × I <sub>GT</sub> )	dI/dt	50	A/μs

Peak gate current	$I_{GM}$	4	A
Average gate power dissipation	$P_{G(AV)}$	1	W
Peak gate power	$P_{GM}$	10	W

**ELECTRICAL CHARACTERISTICS** ( $T_j=25^{\circ}C$  unless otherwise specified)

3 Quadrants

Symbol	Test Condition	Quadrant		Value		Unit
				BW	CW	
$I_{GT}$	$V_D=12V R_L=33\Omega$	I - II -III	MAX	50	35	mA
$V_{GT}$		I - II -III	MAX	1.3		V
$V_{GD}$	$V_D=V_{DRM} T_j=125^{\circ}C$ $R_L=3.3K\Omega$	I - II -III	MIN	0.2		V
$I_L$	$I_G=1.2I_{GT}$	I -III	MAX	80	70	mA
		II		100	80	
$I_H$	$I_T=100mA$		MAX	75	50	mA
dV/dt	$V_D=2/3V_{DRM}$ Gate Open $T_j=125^{\circ}C$		MIN	1000	500	V/ $\mu s$

4 Quadrants

Symbol	Test Condition	Quadrant		Value	Unit
$I_{GT}$	$V_D=12V R_L=33\Omega$	I - II -III	MAX	50	mA
		IV		70	
$V_{GT}$		ALL	MAX	1.3	V
$V_{GD}$	$V_D=V_{DRM} T_j=125^{\circ}C$ $R_L=3.3K\Omega$	ALL	MIN	0.2	V
$I_L$	$I_G=1.2I_{GT}$	I -III	MAX	90	mA
		II -IV		100	
$I_H$	$I_T=100mA$		MAX	80	mA
dV/dt	$V_D=2/3V_{DRM}$ Gate Open $T_j=125^{\circ}C$		MIN	500	V/ $\mu s$

**STATIC CHARACTERISTICS**

Symbol	Parameter		Value(MAX)	Unit
$V_{TM}$	$I_{TM} = 35A$ $t_p = 380\mu s$	$T_j = 25^\circ C$	1.5	V
$I_{DRM}$	$V_D = V_{DRM}$ $V_R = V_{RRM}$	$T_j = 25^\circ C$	5	$\mu A$
$I_{RRM}$		$T_j = 125^\circ C$	3	mA

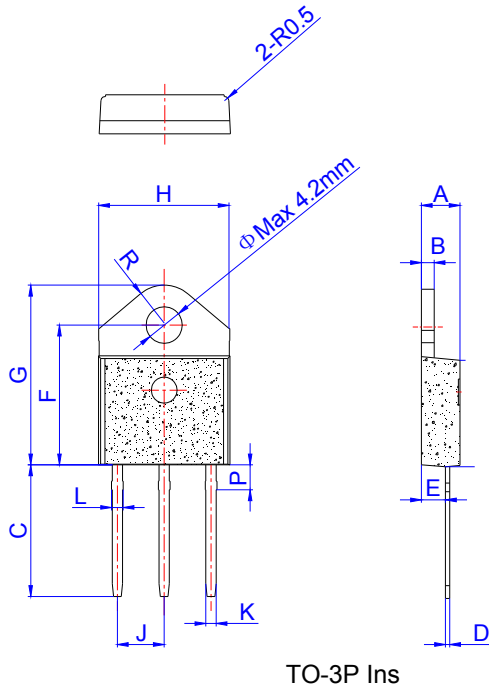
**THERMAL RESISTANCES**

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	junction to case(AC)	TO-3P(Ins)	1.0	$^\circ C/W$
		TO-247J	0.9	

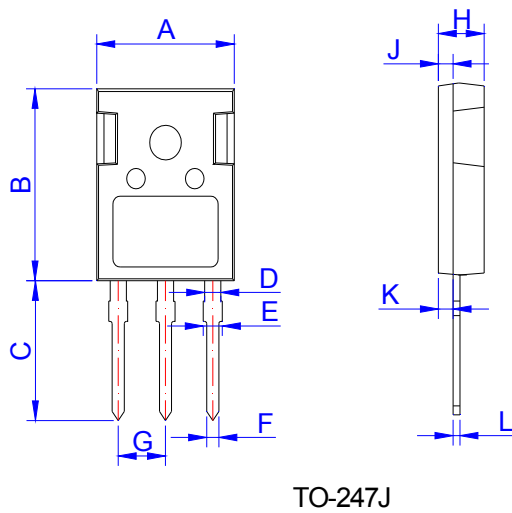
**ORDERING INFORMATION**

J	ST	26	Z	-600	BW
JieJie Microelectronics Co.,Ltd	Triacs	$I_{T(RMS)}: 25A$	Z: TO-3P(Ins) S: TO-247J	600: $V_{DRM} / V_{RRM} \geq 600V$ 800: $V_{DRM} / V_{RRM} \geq 800V$	BW: $I_{GT1-3} \leq 50mA$ CW: $I_{GT1-3} \leq 35mA$ B: $I_{GT1-3} \leq 50mA$ $I_{GT4} \leq 70mA$

PACKAGE MECHANICAL DATA

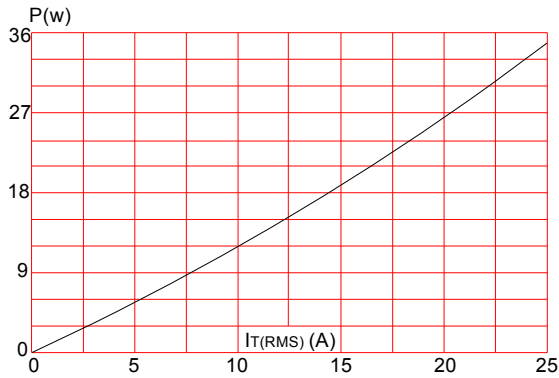


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	1.45		1.55	0.057		0.061
C	14.35		15.60	0.565		0.614
D	0.50		0.70	0.020		0.028
E	2.70		2.90	0.106		0.114
F	15.80		16.50	0.622		0.650
G	20.40		21.10	0.803		0.831
H	15.10		15.50	0.594		0.610
J	5.40		5.65	0.213		0.222
K	1.10		1.40	0.043		0.055
L	1.35		1.50	0.053		0.059
P	2.80		3.00	0.110		0.118
R		4.35			0.171	

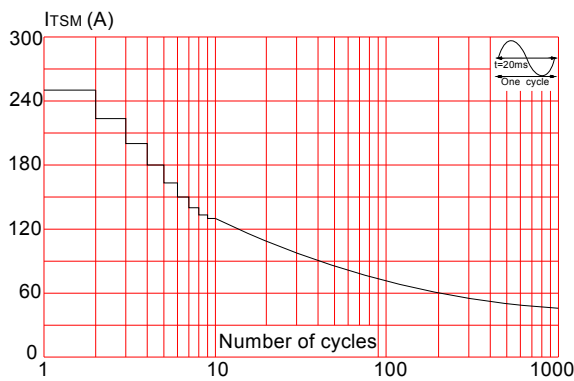


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	15.50	15.80	16.10	0.610	0.622	0.634
B	20.80	21.00	22.20	0.819	0.828	0.874
C	19.70	20.00	20.30	0.776	0.787	0.799
D	1.80	2.00	2.20	0.071	0.079	0.087
E	1.90	2.10	2.30	0.075	0.083	0.091
F	1.00	1.20	1.40	0.039	0.047	0.055
G		5.44			0.214	
H	4.80	5.00	5.20	0.189	0.197	0.205
J	1.90	2.00	2.10	0.075	0.079	0.083
K	2.20	2.35	2.50	0.087	0.093	0.098
L	0.41	0.60	0.79	0.016	0.024	0.031

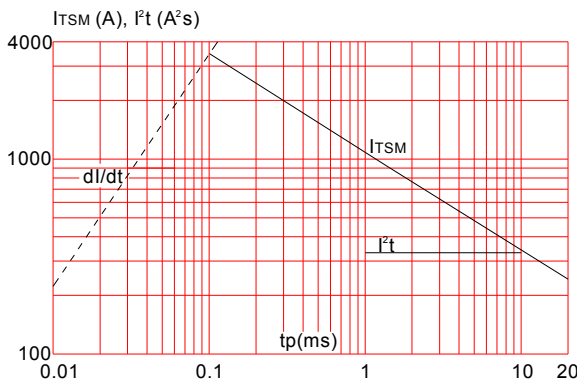
**FIG.1:** Maximum power dissipation versus RMS on-state current



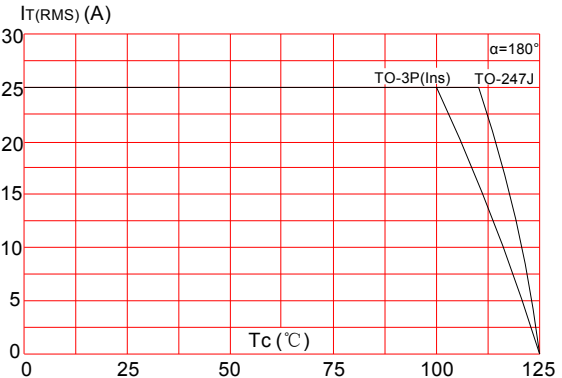
**FIG.3:** Surge peak on-state current versus number of cycles



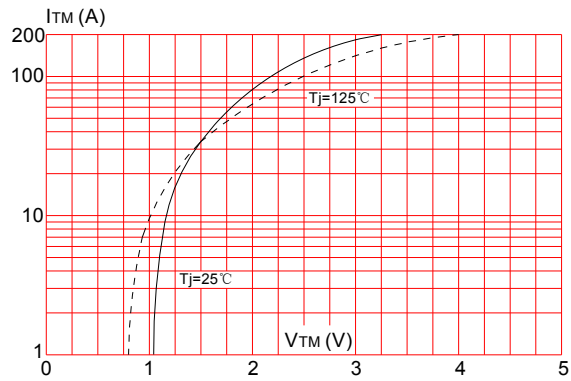
**FIG.5:** Non-repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 20\text{ms}$ , and corresponding value of  $I^2t$  ( $di/dt < 50\text{A}/\mu\text{s}$ )



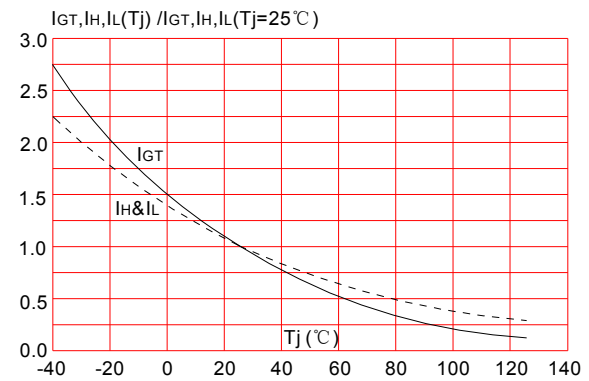
**FIG.2:** RMS on-state current versus case temperature



**FIG.4:** On-state characteristics (maximum values)



**FIG.6:** Relative variations of gate trigger current, holding current and latching current versus junction temperature



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